

June 2010

# FDB8860\_F085

# N-Channel Logic Level PowerTrench® MOSFET 30V, 80A, 2.6m $\Omega$

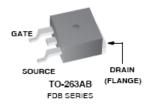
# **Features**

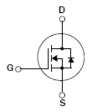
- $R_{DS(ON)} = 1.9 \text{m}\Omega$  (Typ),  $V_{GS} = 5 \text{V}$ ,  $I_D = 80 \text{A}$
- $Q_{g(5)} = 89nC \text{ (Typ)}, V_{GS} = 5V$
- Low Miller Charge
- Low Q<sub>RR</sub> Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- Qualified to AEC Q101
- RoHS Compliant

# **Applications**

- 12V Automotive Load Control
- Start / Alternator Systems
- Electronic Power Steering Systems
- ABS
- DC-DC Converters







# $\textbf{MOSFET Maximum Ratings} \ \, \textbf{T}_{C} = 25^{\circ}\text{C unless otherwise noted}$

Symbol	Parameter	Ratings	Units
$V_{DSS}$	Drain to Source Voltage	30	V
$V_{GS}$	Gate to Source Voltage	±20	V
	Drain Current Continuous (V <sub>GS</sub> = 10V, T <sub>C</sub> < 163°C)	80	А
I <sub>D</sub>	Continuous (V <sub>GS</sub> = 5V, T <sub>C</sub> < 162°C)	80	Α
	Continuous ( $V_{GS} = 10V$ , $T_C = 25^{\circ}C$ , with $R_{\theta JA} = 43^{\circ}C/W$ )	31	Α
	Pulsed	Figure 4	Α
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	947	mJ
D	Power Dissipation	254	W
$P_{D}$	Derate above 25°C	1.7	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to +175	°C

# **Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance Junction to Case	0.59	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (Note 2)	62	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-263,1in <sup>2</sup> copper pad area	43	°C/W

# **Package Marking and Ordering Information**

D	evice Marking	Device	Package	Reel Size	Tape Width	Quantity
	FDB8860	FDB8860_F085	TO-263AB	330mm	24mm	800units

# **Electrical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	octeristics					
$BV_DSS$	Drain to Source Breakdown Voltage	$I_D = 1mA$ , $V_{GS} = 0V$	30	-	-	V
l	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 24V	-	-	1	μА
DSS	Zero date Voltage Brain Guirent	$V_{GS} = 0V$ $T_J = 150^{\circ}C$	-	-	250	μΛ
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA

# **On Characteristics**

V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1	1.7	3	V
		$I_D = 80A, V_{GS} = 10V$	-	1.6	2.3	
		$I_D = 80A, V_{GS} = 5V$	-	1.9	2.6	
R <sub>DS(ON)</sub>	Drain to Source On Resistance	$I_D = 80A, V_{GS} = 4.5V$	-	2.1	2.7	mΩ
		$I_D = 80A, V_{GS} = 10V,$ $T_J = 175^{\circ}C$	-	2.5	3.6	

# **Dynamic Characteristics**

C <sub>ISS</sub>	Input Capacitance	\/ 45\/\\	$V_{DS} = 15V, V_{GS} = 0V,$		9460	12585	pF
C <sub>OSS</sub>	Output Capacitance	─ v <sub>DS</sub> = 15v, v <sub>GS</sub> : — f = 1MHz			1710	2275	pF
C <sub>RSS</sub>	Reverse Transfer Capacitance	1 - 1101112		-	1050	1575	pF
$R_G$	Gate Resistance	f = 1MHz		-	1.8	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V <sub>GS</sub> = 0V to 10V		-	165	214	nC
Q <sub>g(5)</sub>	Total Gate Charge at 5V	$V_{GS} = 0V \text{ to } 5V$		-	89	115	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0V \text{ to } 1V$	$V_{DD} = 15V$ $I_{D} = 80A$	•	9.1	12	nC
$Q_{gs}$	Gate to Source Gate Charge		$I_0 = 60A$ $I_0 = 1.0mA$	-	26	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau		.ge	-	18	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge			-	33	-	nC

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switching	g Characteristics					
t <sub>(on)</sub>	Turn-On Time		-	-	340	ns
t <sub>d(on)</sub>	Turn-On Delay Time		-	14	-	ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>DD</sub> = 15V, I <sub>D</sub> = 80A	-	213	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{DD} = 15V, I_D = 80A$ $V_{GS} = 5V, R_{GS} = 1\Omega$	-	79	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	49	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	192	ns

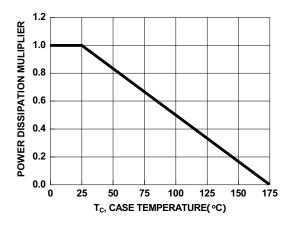
### **Drain-Source Diode Characteristics**

V <sub>SD</sub>	Source to Drain Diode Voltage	I <sub>SD</sub> = 80A	-	-	1.25	V
		I <sub>SD</sub> = 40A	-	-	1.0	٧
t <sub>rr</sub>	Reverse Recovery Time	$I_{SD} = 80A$ , $dI_{SD}/dt = 100A/\mu s$	-	-	43	ns
$Q_{rr}$	Reverse Recovery Charge	$I_{SD} = 80A$ , $dI_{SD}/dt = 100A/\mu s$	-	-	29	nC

**Notes:** 1: Starting  $T_J = 25^{o}C$ , L =0.47mH,  $I_{AS} = 64A$ ,  $V_{DD} = 30V$ ,  $V_{GS} = 10V$ . 2: Pulse width = 100s

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

# **Typical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted



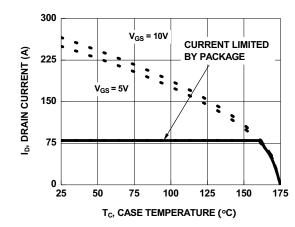


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

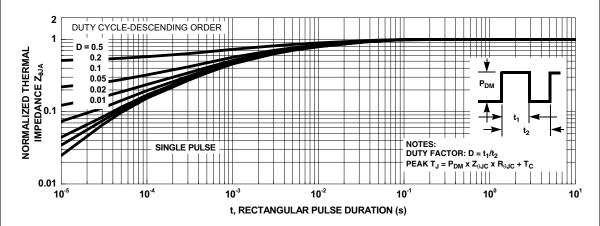


Figure 3. Normalized Maximum Transient Thermal Impedance

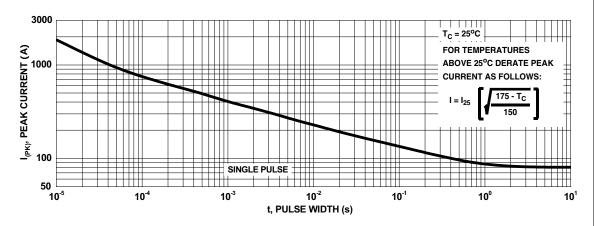
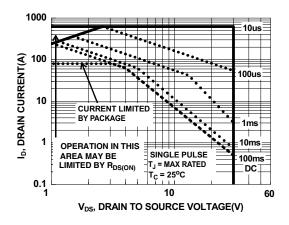


Figure 4. Peak Current Capability

# Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted



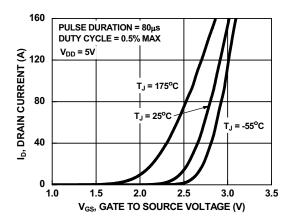
 $\begin{array}{c} 500 \\ \hline \text{If R = 0} \\ \hline \text{T}_{AV} = (\text{L})(\text{I}_{AS})'(1.3\text{*RATED BV}_{DSS} - \text{V}_{DD}) \\ \hline \text{If R } \neq 0 \\ \hline \text{T}_{AV} = (\text{L}/\text{R})\ln[(\text{I}_{AS}\text{*R})/(1.3\text{*RATED BV}_{DSS} - \text{V}_{DD}) + 1] \\ \hline \\ \text{STARTING T}_{J} = 25^{\circ}\text{C} \\ \hline \\ \text{STARTING T}_{J} = 150^{\circ}\text{C} \\ \hline \\ \text{STARTING T}_{J$ 

Figure 5. Forward Bias Safe Operating Area

NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability



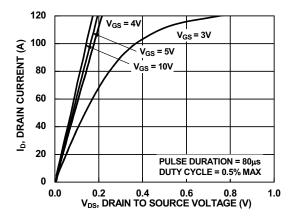
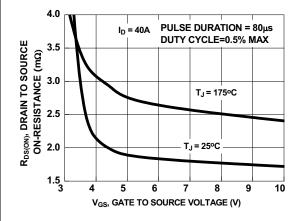


Figure 7. Transfer Characteristics

Figure 8. Saturation Characteristics



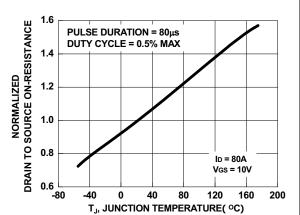


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

# Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

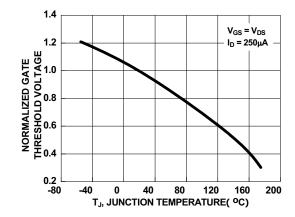
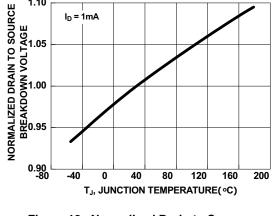


Figure 11. Normalized Gate Threshold Voltage vs **Junction Temperature** 



1.10

Figure 12. Normalized Drain to Source **Breakdown Voltage vs Junction Temperature** 

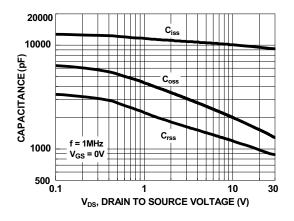


Figure 13. Capacitance vs Drain to Source Voltage

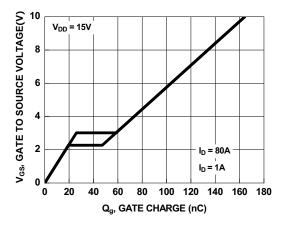


Figure 14. Gate Charge vs Gate to Source Voltage





### **TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

 $\begin{array}{lll} \mbox{AccuPower}^{\mbox{\tiny TM}} & \mbox{F-PFS}^{\mbox{\tiny TM}} \\ \mbox{Auto-SPM}^{\mbox{\tiny TM}} & \mbox{FRFET}^{\mbox{\tiny 8}} \end{array}$ 

Build it Now™ Global Power Resource SM CorePLUS™ Green FPS™

CorePOWER™ Green FPS™ e-Series™

CROSSVOLT™ Gmax™
CTL™ GTO™

Current Transfer Logic™ IntelliMAX™
DEUXPEED® ISOPLANAR™

DEUXPEED® ISOPLANAR™

Dual Cool™ MegaBuck™

EcoSPARK® MICROCOUPLER™

EfficientMax™ MicroFET™

ESBC™ MicroPak™

Fairchild® MillerDrive™
Fairchild Semiconductor® MotionMax™
FACT Quiet Series™ OptoHIT™
FACT® OPTOLOGIC®
FAST® OPTOLANAR®

FastvCore™ FETBench™ FlashWriter®\*

FlashWriter PDP SPM<sup>TM</sup>

Power-SPM™ PowerTrench® PowerXS™

Programmable Active Droop™

QFĔT<sup>®</sup>
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™ SPM®

SPM
STEALTH™
SUPERSOT™-3
SUPERSOT™-6
SUPERSOT™-8
SUPERSOT™-8
SUPEMOS™
SyncFET™
Sync-Lock™

The Power Franchise®

bwer

franchise

TinvBoost™

TinyBuck™ TinyCalc™

TinyLogic<sup>®</sup>

TINYOPTO™

TinyPower™

\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

### As used herein:

- Life support devices or systems are devices or systems which, (a) are
  intended for surgical implant into the body or (b) support or sustain life,
  and (c) whose failure to perform when properly used in accordance
  with instructions for use provided in the labeling, can be reasonably
  expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

### **ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

### PRODUCT STATUS DEFINITIONS

### **Definition of Terms**

Datasheet Identification   Product Status		Definition		
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.		
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.		
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.		
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.		

Rev. I48